RB10-E

SINGLE PHASE GLASS PASSIVATED SURFACE MOUNT FLAT BRIDGE RECTIFIER

VOLTAGE: 1000V **CURRENT: 1.0A**

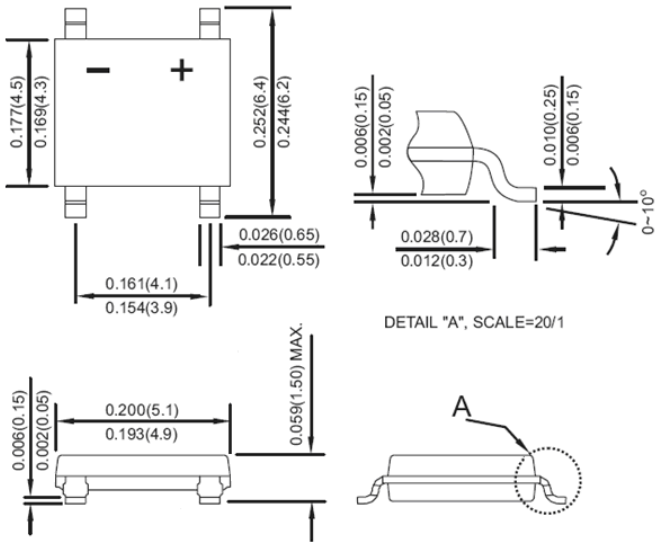
FEATURE

Ideal for printed circuit board
Glass passivated chip
Reliable low cost construction utilizing molded plastic technique
High surge current capability
Small size, simple installation
High temperature soldering guaranteed: 260℃/10seconds
Halogen Free

MECHANICAL DATA

Terminal: Plated leads solderable per J-STD-002
Case:UL-94 Class V-0 recognized Halogen Free Epoxy
Polarity: Polarity symbol marked on body

LBF



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half -wave, 60HZ, resistive or inductive load rating at 25°C, unless otherwise stated)

	Symbol	RB10-E	Units
Maximum Recurrent Peak Reverse Voltage	Vrrm	1000	V
Maximum RMS Voltage	Vrms	700	V
Maximum DC blocking Voltage	VDC	1000	V
Maximum Average Forward Rectified Current — on aluminum substrate on glass-epoxy P.C.B.	If(av)	1.0 0.8	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	Ifsm	30	A
Maximum Instantaneous Forward Voltage at forward current 0.4A per diode	Vf	0.95	V
Rating for fusing(t＜8.3ms)	I^2t	3.9	A^2sec
Maximum DC Reverse Current Ta =25℃ at rated DC blocking voltage Ta =125℃	Ir	5.0 100.0	μA
Typical Thermal resistance — junction to lead on aluminum substrate on glass-epoxy P.C.B. junction to case (Note1)	Rth(jl) Rth(ja) Rth(jc)	25 62.5 80 20	℃/W
Storage and Operating Junction Temperature Range	Tstg, Tj	-55 to +150	℃

Note:
1.Thermal Resistance from Junction to terminal mounted on 5×5mm copper pad area

RATINGS AND CHARACTERISTIC CURVES RB10-E

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

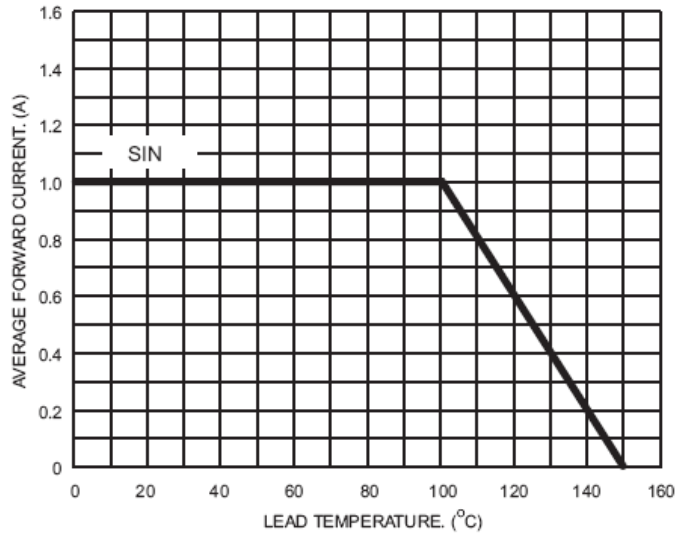


FIG.2- TYPICAL FORWARD CHARACTERISTICS

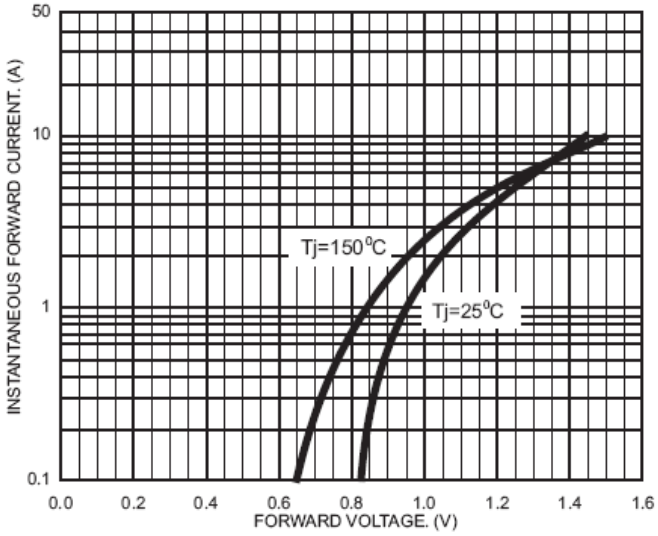


FIG.3- MAXIMUM FORWARD CURRENT DERATING CURVE

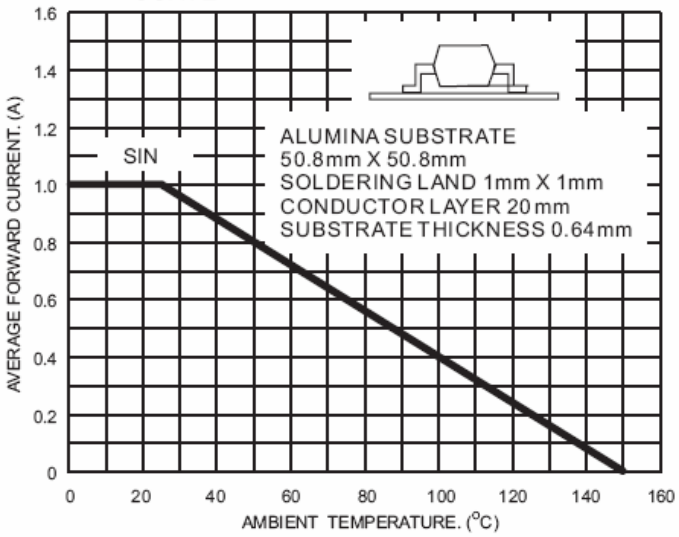


FIG.4- FORWARD POWER DISSIPATION

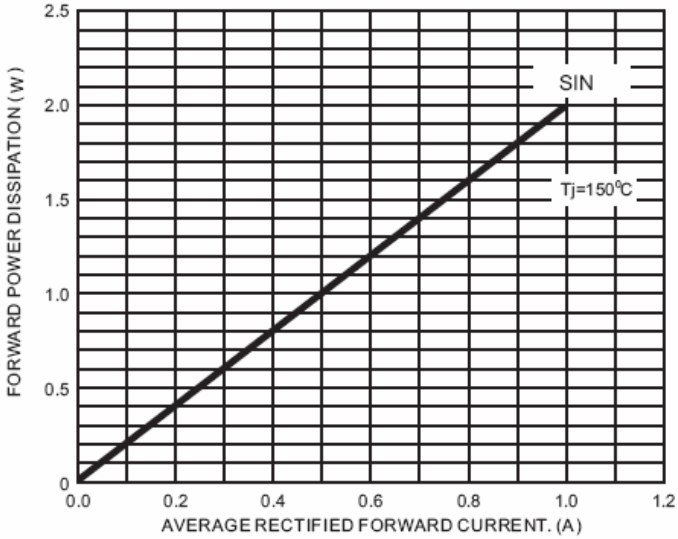


FIG.5- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT